



PATENT
29347/990488

**IN THE UNITED STATES PATENT
AND TRADEMARK OFFICE**

Applicants: Jeun, et al.

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20231 on this date:
December 4, 2001

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Serial No.: 09/677,558

Filed: September 29, 2000

For: Semiconductor Power Module
Having an Electrically Insulating
Heat Sink and Method of
Manufacturing the Same

Docket No.: 29347/990488

Art Unit: 2811

Examiner: D. Nguyen

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
Washington, D.C. 20231

Sir:

The patent listed on the enclosed PTO Form-1449 is submitted pursuant to 37 CFR §§ 1.56, 1.97, and 1.98. A copy of the patent is enclosed.

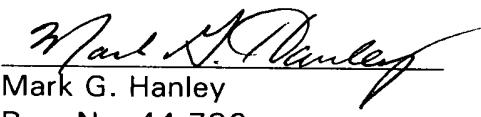
Pursuant to 37 C.F.R. § 1.97(c), the \$180 fee set forth in 37 C.F.R. § 1.17(p) for consideration of this Supplemental Information Disclosure Statement is included herewith.

The Commissioner is authorized to charge any fee deficiency required by this paper, or credit any overpayment, to Deposit Account No. 13-2855. A copy of this paper is enclosed.

Respectfully submitted,

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